

**PATENT ABSTRACTS OF JAPAN**(11)Publication number : **06-061293**(43)Date of publication of application : **04.03.1994**

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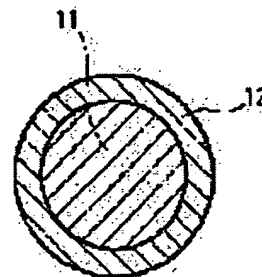
H01L 21/60

H01L 21/60

(21)Application number : **04-235326**(71)Applicant : **NIPPON STEEL CORP**(22)Date of filing : **11.08.1992**(72)Inventor : **NITTA NORIO****(54) SEMICONDUCTOR DEVICE****(57)Abstract:**

**PURPOSE:** To overcome restrictions on packaging, and to provide a semiconductor device having a packaging part in which a space for packaging interconnections is given the functions of a signal noise filter and an equivalent parallel capacitor.

**CONSTITUTION:** Material having a high magnetic permeability 12 is arranged in an interconnection packaging part used for the electrical connection between an IC chip and an external connecting terminal. The interconnection packaging part is made up of a TAB lead, a bonding wire or the periphery of a pad. The magnetic permeability surrounding a bonding wire 1 which acts as the interconnection packaging part is made larger, so that the inductance of an interconnection path is made larger than an ordinary interconnection. Thereby, the interconnection packaging part are provided with both a filtering function for eliminating high frequency noise and an equivalent smoothing capacitor function.

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